

ABSTRACT OF THE DISCLOSURE

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A system that decapsulates an integrated circuit  
package while the package is mounted to a printed  
circuit board. The system includes a tray that  
supports a printed circuit board which has at least one  
integrated circuit package mounted to the board.  
Mounted to the tray is a clamp which clamps an  
injection head to the top of the package. The  
injection head is coupled to a source of decapsulation  
fluid which is sprayed onto the package. The  
decapsulation fluid is circulated across the package to  
remove the package material and expose the underlying  
integrated circuit. The injection head has a gasket  
that is pressed onto the package to prevent the fluid  
from leaking onto the printed circuit board. After the  
plastic is decapsulated the head can be removed from  
the package so that the integrated circuit can be  
tested while the circuit is connected to the printed  
circuit board.